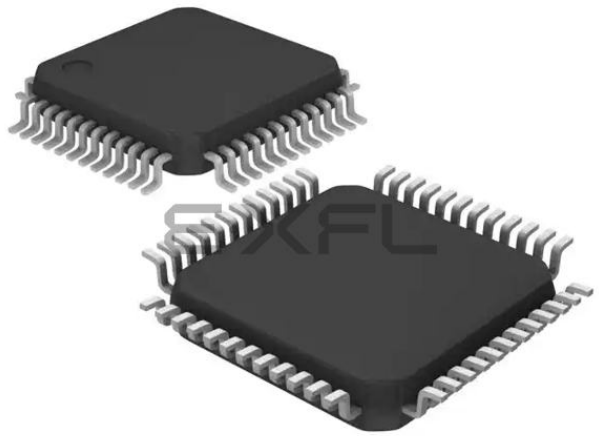

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SmartCard, SPI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	40
Program Memory Size	40KB (40K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11u34fbd48-311

Table 1. Ordering information *…continued*

Type number	Package		
	Name	Description	Version
LPC11U36FBD64/401	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC11U37FBD48/401	LQFP48	plastic low profile quad flat package; 48 leads; body 7 × 7 × 1.4 mm	SOT313-2
LPC11U37HFBD64/401	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2
LPC11U37FBD64/501	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2

4.1 Ordering options

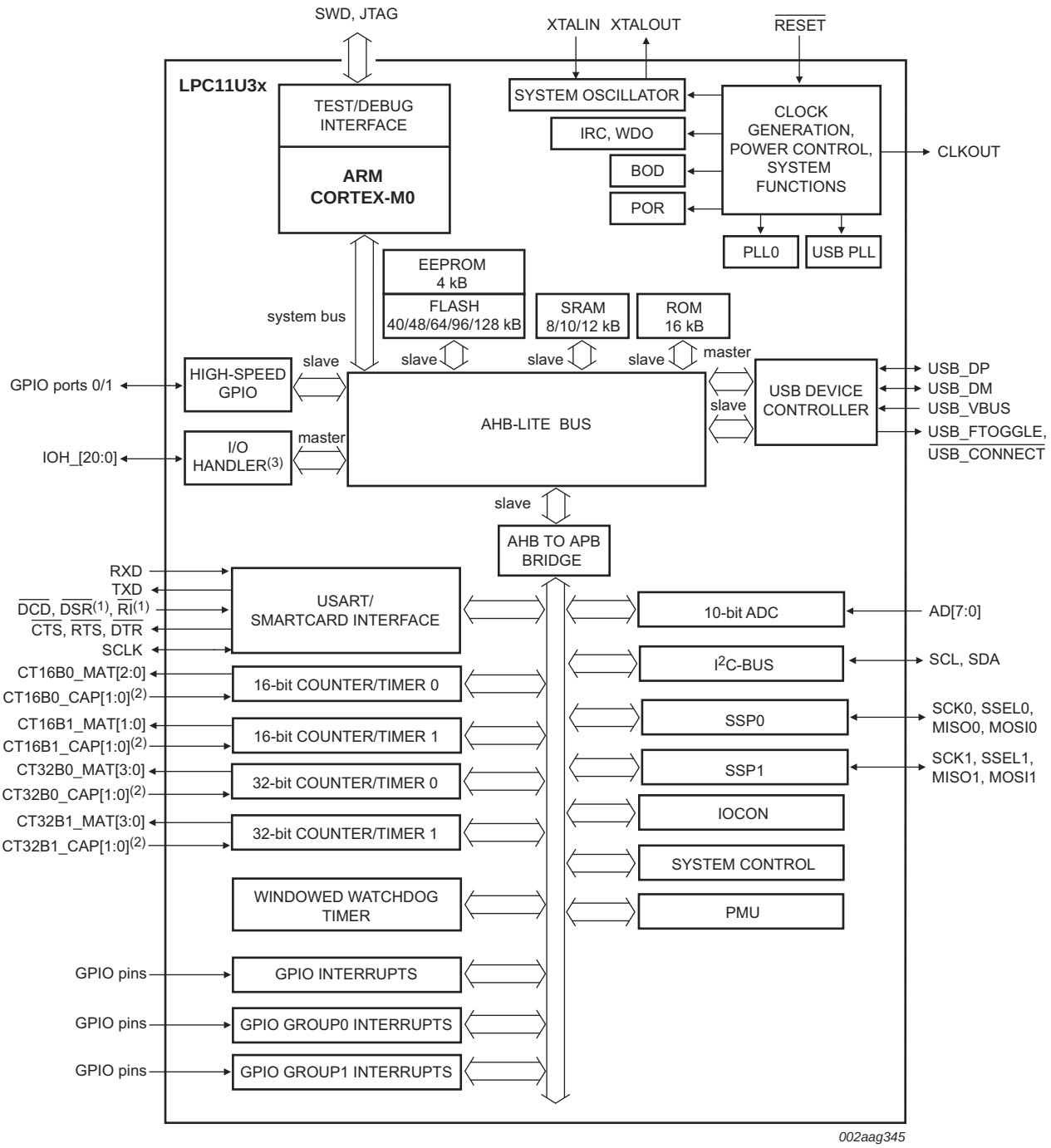
Table 2. Ordering options

Type number	Flash in kB	EEPROM in kB	SRAM0 in kB	USB SRAM in kB	SRAM1 in kB	Total SRAM in kB[1]	I/O Handler	USART	I²C-bus FM+	SSP	USB device	ADC channels	GPIO pins
LPC11U34FHN33/311	40	4	8	-	-	8	no	1	1	2	1	8	26
LPC11U34FBD48/311	40	4	8	-	-	8	no	1	1	2	1	8	40
LPC11U34FHN33/421	48	4	8	2	-	10	no	1	1	2	1	8	26
LPC11U34FBD48/421	48	4	8	2	-	10	no	1	1	2	1	8	40
LPC11U35FHN33/401	64	4	8	2	-	10	no	1	1	2	1	8	26
LPC11U35FBD48/401	64	4	8	2	-	10	no	1	1	2	1	8	40
LPC11U35FBD64/401	64	4	8	2	-	10	no	1	1	2	1	8	54
LPC11U35FHI33/501	64	4	8	2	2[1]	12	no	1	1	2	1	8	26
LPC11U35FET48/501	64	4	8	2	2[1]	12	no	1	1	2	1	8	40
LPC11U36FBD48/401	96	4	8	2	-	10	no	1	1	2	1	8	40
LPC11U36FBD64/401	96	4	8	2	-	10	no	1	1	2	1	8	54
LPC11U37FBD48/401	128	4	8	2	-	10	no	1	1	2	1	8	40
LPC11U37HFBD64/401	128	4	8	2	2[2]	10	yes	1	1	2	1	8	54
LPC11U37FBD64/501	128	4	8	2	2[1]	12	no	1	1	2	1	8	54

[1] For general-purpose use.

[2] For I/O Handler use only.

5. Block diagram



(1) Not available on HVQFN33 packages.

(2) CT16B0_CAP1, CT16B1_CAP1 available on LQFP64 packages only; CT32B0_CAP1 available on TFBGA48, LQFP48, and LQFP64 packages only; CT32B1_CAP1 available in TFBGA48/LQFP64 packages only.

(3) LPC11U37HFBD64/401 only.

Fig 1. Block diagram

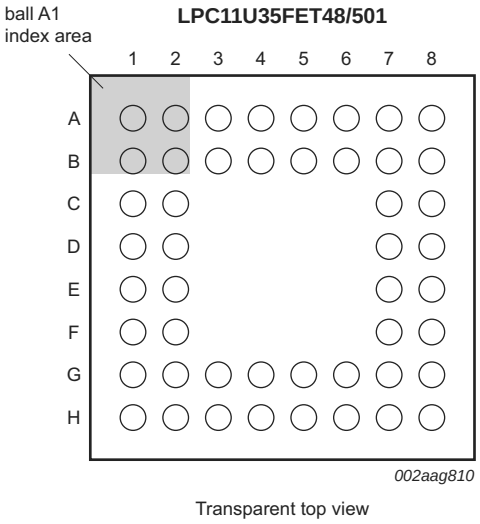


Fig 3. Pin configuration (TFBGA48)

Table 3. Pin description

Symbol	Pin HVQFN33	Pin TFBGA48	Pin LQFP48	Pin LQFP64	Reset state [1]	Type	Description
PIO0_17/$\overline{\text{RTS}}$/ CT32B0_CAP0/SCLK	30	A3	45	60 [3]	I; PU	I/O	**PIO0_17 —** General purpose digital input/output pin.
					-	O	**$\overline{\text{RTS}}$ —** Request To Send output for USART.
					-	I	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
					-	I/O	**SCLK —** Serial clock input/output for USART in synchronous mode.
PIO0_18/RXD/ CT32B0_MAT0	31	B3	46	61 [3]	I; PU	I/O	**PIO0_18 —** General purpose digital input/output pin.
					-	I	**RXD —** Receiver input for USART. Used in UART ISP mode.
					-	O	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO0_19/TXD/ CT32B0_MAT1	32	B2	47	62 [3]	I; PU	I/O	**PIO0_19 —** General purpose digital input/output pin.
					-	O	**TXD —** Transmitter output for USART. Used in UART ISP mode.
					-	O	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO0_20/CT16B1_CAP0	7	F2	9	11 [3]	I; PU	I/O	**PIO0_20 —** General purpose digital input/output pin.
					-	I	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO0_21/CT16B1_MAT0/ MOSI1	12	G4	17	22 [3]	I; PU	I/O	**PIO0_21 —** General purpose digital input/output pin.
					-	O	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
					-	I/O	**MOSI1 —** Master Out Slave In for SSP1.
PIO0_22/AD6/ CT16B1_MAT1/MISO1	20	E8	30	40 [6]	I; PU	I/O	**PIO0_22 —** General purpose digital input/output pin.
					-	I	**AD6 —** A/D converter, input 6.
					-	O	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
					-	I/O	**MISO1 —** Master In Slave Out for SSP1.
PIO0_23/AD7/IOH_9	27	A5	42	56 [6]	I; PU	I/O	**PIO0_23 —** General purpose digital input/output pin.
					-	I	**AD7 —** A/D converter, input 7.
					-	I/O	**IOH_9 —** I/O Handler input/output 9. (LPC11U37HFBD64/401 only.)
PIO1_0/CT32B1_MAT0/ IOH_10	-	-	-	1 [3]	I; PU	I/O	**PIO1_0 —** General purpose digital input/output pin.
					-	O	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
					-	I/O	**IOH_10 —** I/O Handler input/output 10. (LPC11U37HFBD64/401 only.)
PIO1_1/CT32B1_MAT1/ IOH_11	-	-	-	17 [3]	I; PU	I/O	**PIO1_1 —** General purpose digital input/output pin.
					-	O	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
					-	I/O	**IOH_11 —** I/O Handler input/output 11. (LPC11U37HFBD64/401 only.)
PIO1_2/CT32B1_MAT2/ IOH_12	-	-	-	34 [3]	I; PU	I/O	**PIO1_2 —** General purpose digital input/output pin.
					-	O	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
					-	I/O	**IOH_12 —** I/O Handler input/output 12. (LPC11U37HFBD64/401 only.)

- Software enables the WWDT, but a hardware reset or a watchdog reset/interrupt is required to disable the WWDT.
- Incorrect feed sequence causes reset or interrupt, if enabled.
- Flag to indicate watchdog reset.
- Programmable 24-bit timer with internal prescaler.
- Selectable time period from ($T_{cy(WDCLK)} \times 256 \times 4$) to ($T_{cy(WDCLK)} \times 2^{24} \times 4$) in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) source can be selected from the IRC or the dedicated watchdog oscillator (WDO). The clock source selection provides a wide range of potential timing choices of watchdog operation under different power conditions.

7.18 Clocking and power control

7.18.1 Integrated oscillators

The LPC11U3x include three independent oscillators: the system oscillator, the Internal RC oscillator (IRC), and the watchdog oscillator. Each oscillator can be used for more than one purpose as required in a particular application.

Following reset, the LPC11U3x operates from the internal RC oscillator until software switches to a different clock source. The IRC allows the system to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 7 for an overview of the LPC11U3x clock generation.

7.18.1.2 System oscillator

The system oscillator can be used as the clock source for the CPU, with or without using the PLL. On the LPC11U3x, use the system oscillator to provide the clock source to USB.

The system oscillator operates at frequencies of 1 MHz to 25 MHz. This frequency can be boosted to a higher frequency, up to the maximum CPU operating frequency, by the system PLL.

7.18.1.3 Watchdog oscillator

The watchdog oscillator can be used as a clock source that directly drives the CPU, the watchdog timer, or the CLKOUT pin. The watchdog oscillator nominal frequency is programmable between 9.4 kHz and 2.3 MHz. The frequency spread over processing and temperature is ±40 % (see also Table 13).

7.18.2 System PLL and USB PLL

The LPC11U3x contain a system PLL and a dedicated PLL for generating the 48 MHz USB clock. The system and USB PLLs are identical.

The PLL accepts an input clock frequency in the range of 10 MHz to 25 MHz. The input frequency is multiplied up to a high frequency with a Current Controlled Oscillator (CCO). The multiplier can be an integer value from 1 to 32. The CCO operates in the range of 156 MHz to 320 MHz. To support this frequency range, an additional divider keeps the CCO within its frequency range while the PLL is providing the desired output frequency. The output divider can be set to divide by 2, 4, 8, or 16 to produce the output clock. The PLL output frequency must be lower than 100 MHz. Since the minimum output divider value is 2, it is insured that the PLL output has a 50 % duty cycle. The PLL is turned off and bypassed following a chip reset. Software can enable the PLL later. The program must configure and activate the PLL, wait for the PLL to lock, and then connect to the PLL as a clock source. The PLL settling time is 100 μs.

7.18.3 Clock output

The LPC11U3x feature a clock output function that routes the IRC oscillator, the system oscillator, the watchdog oscillator, or the main clock to an output pin.

7.18.4 Wake-up process

The LPC11U3x begin operation by using the 12 MHz IRC oscillator as the clock source at power-up and when awakened from Deep power-down mode . This mechanism allows chip operation to resume quickly. If the application uses the main oscillator or the PLL, software must enable these components and wait for them to stabilize. Only then can the system use the PLL and main oscillator as a clock source.

7.18.5 Power control

The LPC11U3x support various power control features. There are four special modes of processor power reduction: Sleep mode, Deep-sleep mode, Power-down mode, and Deep power-down mode. The CPU clock rate can also be controlled as needed by changing clock sources, reconfiguring PLL values, and/or altering the CPU clock divider value. This power control mechanism allows a trade-off of power versus processing speed based on application requirements. In addition, a register is provided for shutting down the clocks to individual on-chip peripherals. This register allows fine-tuning of power

7.19 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug functions are supported in addition to a standard JTAG boundary scan. The ARM Cortex-M0 is configured to support up to four breakpoints and two watch points.

The $\overline{\text{RESET}}$ pin selects between the JTAG boundary scan ($\overline{\text{RESET}}$ = LOW) and the ARM SWD debug ($\overline{\text{RESET}}$ = HIGH). The ARM SWD debug port is disabled while the LPC11U3x is in reset.

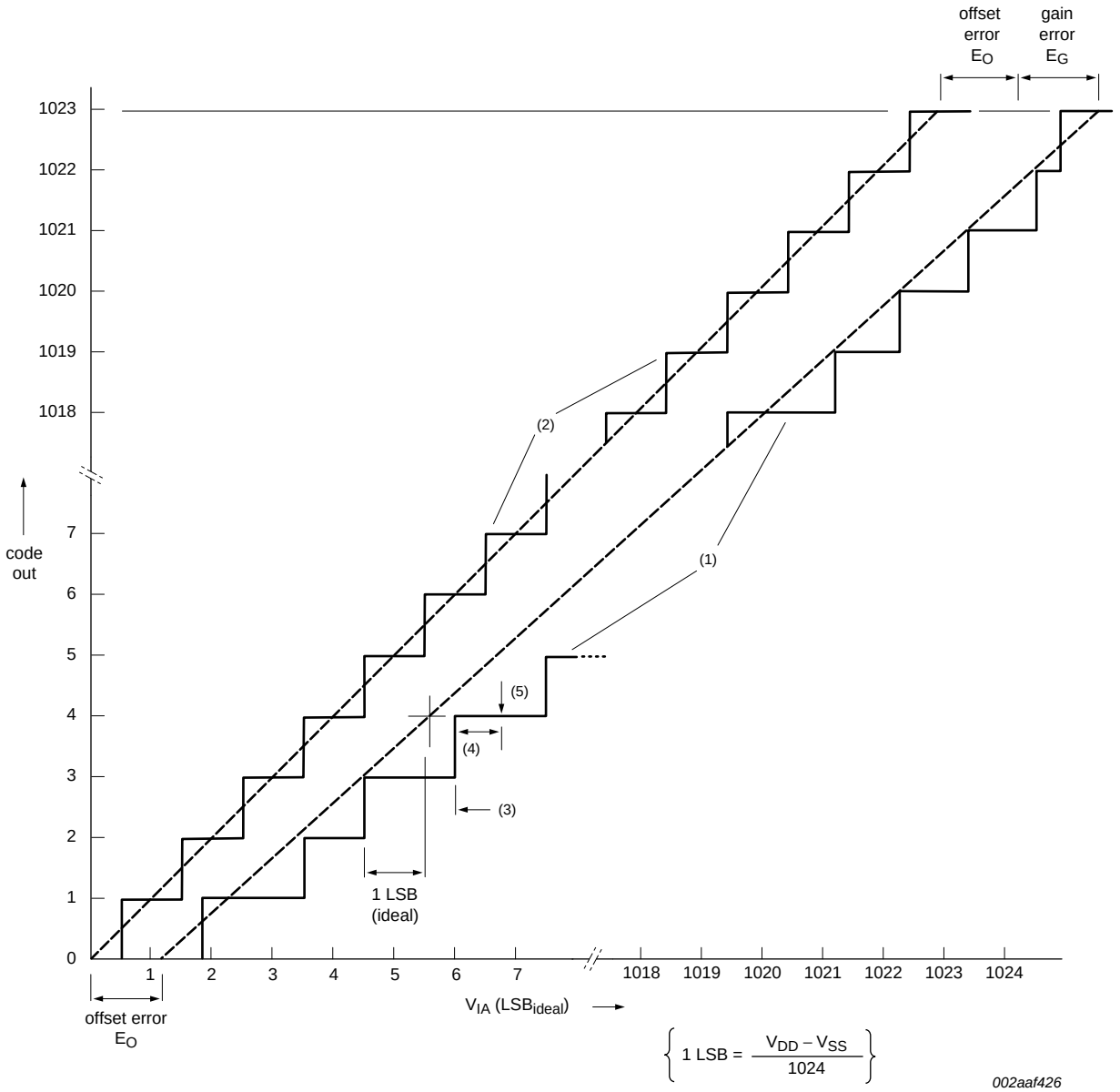
To perform boundary scan testing, follow these steps:

1. Erase any user code residing in flash.
2. Power up the part with the $\overline{\text{RESET}}$ pin pulled HIGH externally.
3. Wait for at least 250 μs.
4. Pull the $\overline{\text{RESET}}$ pin LOW externally.
5. Perform boundary scan operations.
6. Once the boundary scan operations are completed, assert the $\overline{\text{TRST}}$ pin to enable the SWD debug mode, and release the $\overline{\text{RESET}}$ pin (pull HIGH).

Remark: The JTAG interface cannot be used for debug purposes.

Table 5. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.0 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	3	-	-	mA
I_{OHS}	HIGH-level short-circuit output current	V_{OH} = 0 V [13]	-	-	−45	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [13]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA
I_{pu}	pull-up current	V_I = 0 V; 2.0 V ≤ V_{DD} ≤ 3.6 V	−15	−50	−85	μA
		1.8 V ≤ V_{DD} < 2.0 V	−10	−50	−85	μA
		V_{DD} < V_I < 5 V	0	0	0	μA
High-drive output pin (PIO0_7)						
I_{IL}	LOW-level input current	V_I = 0 V; on-chip pull-up resistor disabled	-	0.5	10	nA
I_{IH}	HIGH-level input current	V_I = V_{DD}; on-chip pull-down resistor disabled	-	0.5	10	nA
I_{OZ}	OFF-state output current	V_O = 0 V; V_O = V_{DD}; on-chip pull-up/down resistors disabled	-	0.5	10	nA
V_I	input voltage	pin configured to provide a digital function; V_{DD} ≥ 1.8 V [11] [12]	0	-	5.0	V
		V_{DD} = 0 V	0	-	3.6	V
V_O	output voltage	output active	0	-	V_{DD}	V
V_{IH}	HIGH-level input voltage		0.7V_{DD}	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.3V_{DD}	V
V_{hys}	hysteresis voltage		0.4	-	-	V
V_{OH}	HIGH-level output voltage	2.5 V ≤ V_{DD} ≤ 3.6 V; I_{OH} = −20 mA	V_{DD} − 0.4	-	-	V
		1.8 V ≤ V_{DD} < 2.5 V; I_{OH} = −12 mA	V_{DD} − 0.4	-	-	V
V_{OL}	LOW-level output voltage	2.0 V ≤ V_{DD} ≤ 3.6 V; I_{OL} = 4 mA	-	-	0.4	V
		1.8 V ≤ V_{DD} < 2.0 V; I_{OL} = 3 mA	-	-	0.4	V
I_{OH}	HIGH-level output current	V_{OH} = V_{DD} − 0.4 V; 2.5 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.5 V	12	-	-	mA
I_{OL}	LOW-level output current	V_{OL} = 0.4 V 2.0 V ≤ V_{DD} ≤ 3.6 V	4	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	3	-	-	mA
I_{OLS}	LOW-level short-circuit output current	V_{OL} = V_{DD} [13]	-	-	50	mA
I_{pd}	pull-down current	V_I = 5 V	10	50	150	μA



(1) Example of an actual transfer curve.

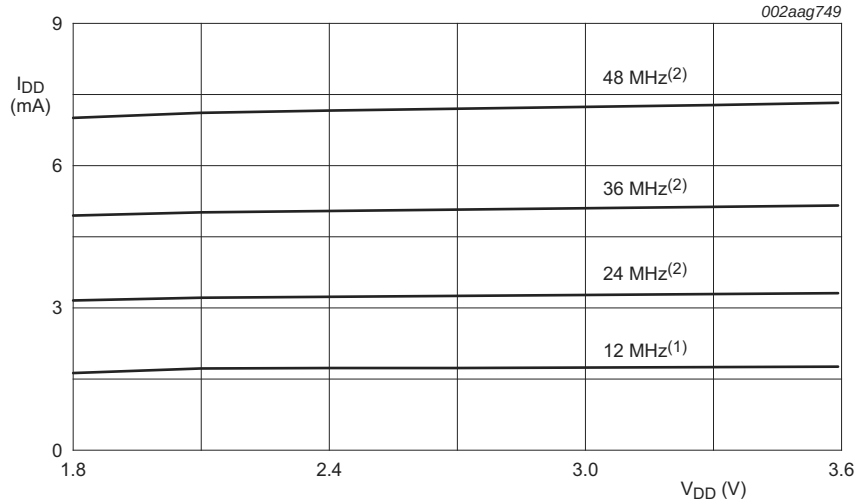
(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 8. ADC characteristics

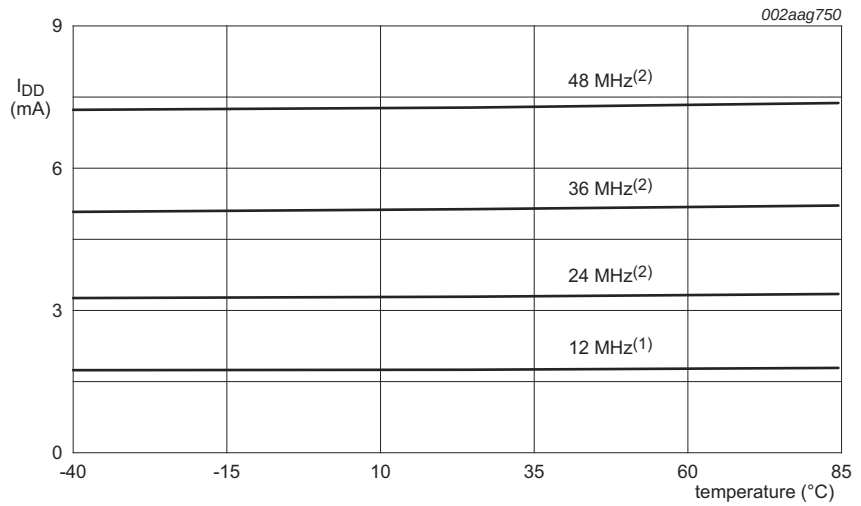


Conditions: T_{amb} = 25 °C; Active mode entered executing code `while(1){}` from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode; USB_DP and USB_DM pulled LOW externally.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 9. Typical supply current versus regulator supply voltage V_{DD} in active mode

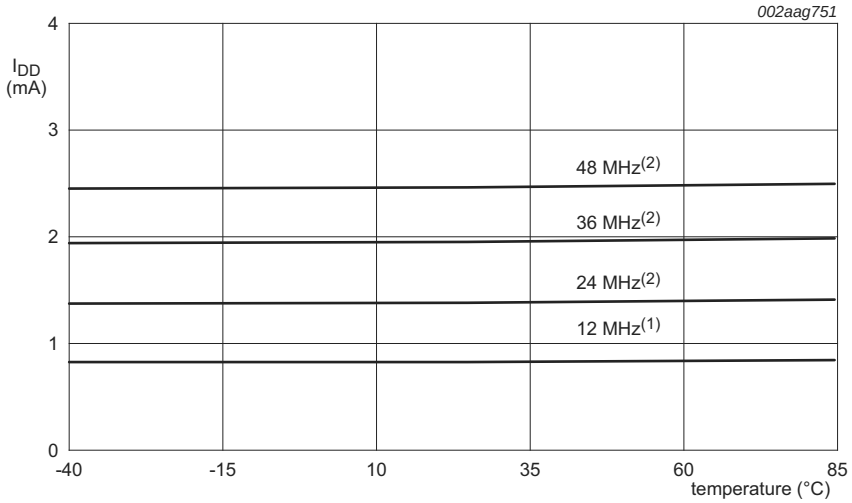


Conditions: V_{DD} = 3.3 V; Active mode entered executing code `while(1){}` from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode; USB_DP and USB_DM pulled LOW externally.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 10. Typical supply current versus temperature in Active mode

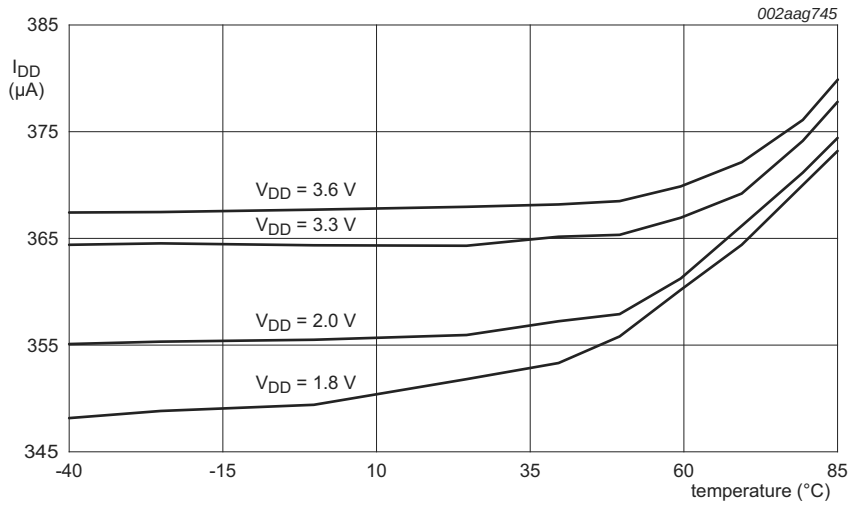


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode; USB_DP and USB_DM pulled LOW externally.

(1) System oscillator and system PLL disabled; IRC enabled.

(2) System oscillator and system PLL enabled; IRC disabled.

Fig 11. Typical supply current versus temperature in Sleep mode



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; USB_DP and USB_DM pulled LOW externally.

Fig 12. Typical supply current versus temperature in Deep-sleep mode

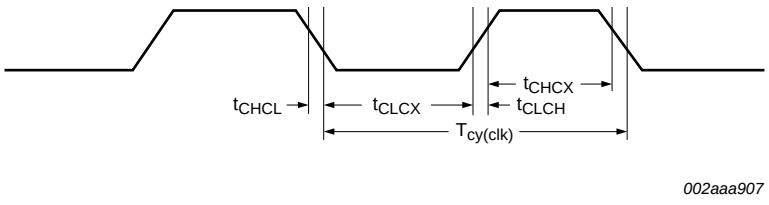


Fig 21. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

10.3 Internal oscillators

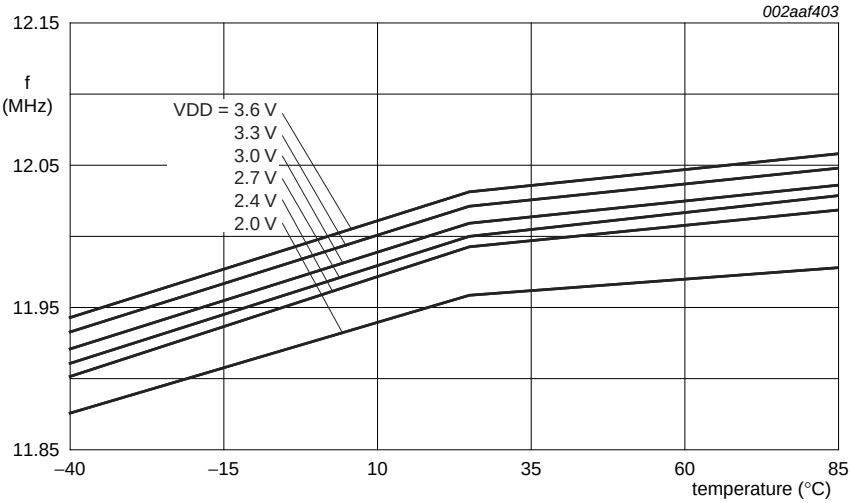
Table 12. Dynamic characteristics: IRC

T_{amb} = −40 °C to +85 °C; 2.7 V ≤ V_{DD} ≤ 3.6 V[1].

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-	11.88	12	12.12	MHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



Conditions: Frequency values are typical values. 12 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ V_{DD} ≤ 3.6 V and T_{amb} = −40 °C to +85 °C. Variations between parts may cause the IRC to fall outside the 12 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 22. Internal RC oscillator frequency versus temperature

Table 13. Dynamic characteristics: Watchdog oscillator

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$f_{osc(int)}$	internal oscillator frequency	DIVSEL = 0x1F, FREQSEL = 0x1 in the WDTOSCCTRL register; [2][3]	-	9.4	-	kHz
		DIVSEL = 0x00, FREQSEL = 0xF in the WDTOSCCTRL register [2][3]	-	2300	-	kHz

[1] Typical ratings are not guaranteed. The values listed are at nominal supply voltages.

10.7 USB interface

Table 17. Dynamic characteristics: USB pins (full-speed)

C_L = 50 pF; R_{pu} = 1.5 kΩ on D+ to V_{DD}; 3.0 V ≤ V_{DD} ≤ 3.6 V.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_r	rise time	10 % to 90 %	8.5	-	13.8	ns
t_f	fall time	10 % to 90 %	7.7	-	13.7	ns
t_{FRFM}	differential rise and fall time matching	t_r / t_f	-	-	109	%
V_{CRS}	output signal crossover voltage		1.3	-	2.0	V
t_{FEOPT}	source SE0 interval of EOP	see Figure 26	160	-	175	ns
t_{FDEOP}	source jitter for differential transition to SE0 transition	see Figure 26	−2	-	+5	ns
t_{JR1}	receiver jitter to next transition		−18.5	-	+18.5	ns
t_{JR2}	receiver jitter for paired transitions	10 % to 90 %	−9	-	+9	ns
t_{EOPR}	EOP width at receiver	must accept as EOP; see Figure 26 [1]	82	-	-	ns

[1] Characterized but not implemented as production test. Guaranteed by design.

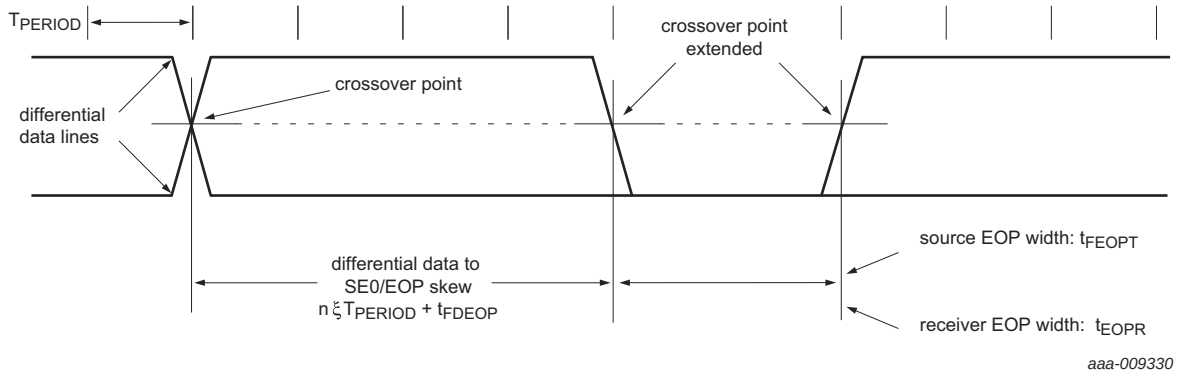


Fig 26. Differential data-to-EOP transition skew and EOP width

11.5 Reset pad configuration

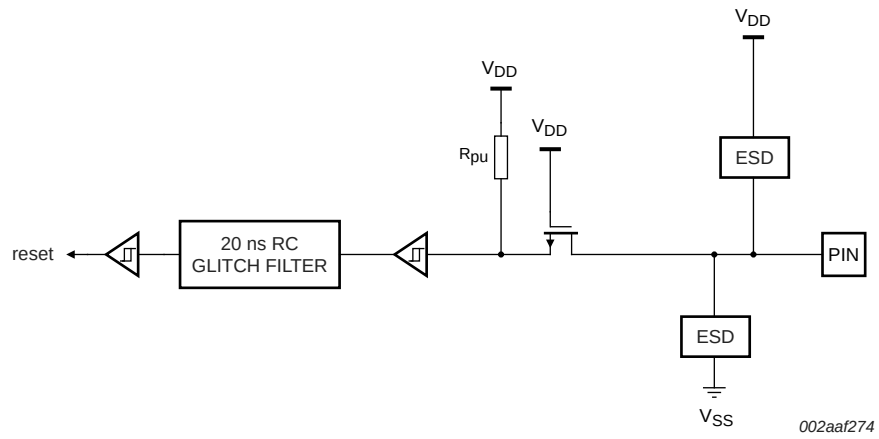


Fig 32. Reset pad configuration

11.6 ADC effective input impedance

A simplified diagram of the ADC input channels can be used to determine the effective input impedance seen from an external voltage source. See Figure 33.

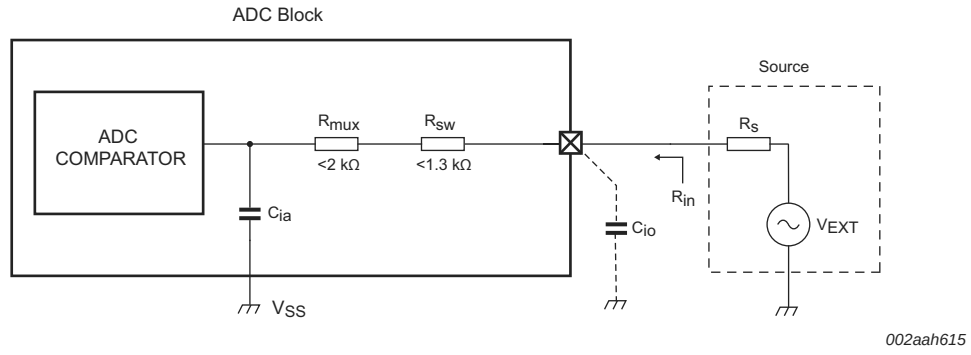


Fig 33. ADC input channel

The effective input impedance, R_{in}, seen by the external voltage source, V_{EXT}, is the parallel impedance of ($(1/f_s \times C_{ia}) + R_{mux} + R_{sw}$) and ($1/f_s \times C_{io}$), and can be calculated using Equation 1 with

f_s = sampling frequency

C_{ia} = ADC analog input capacitance

R_{mux} = analog mux resistance

R_{sw} = switch resistance

C_{io} = pin capacitance

$$R_{in} = \left(\frac{1}{f_s \times C_{ia}} + R_{mux} + R_{sw}\right) \parallel \left(\frac{1}{f_s \times C_{io}}\right) \quad (1)$$

Under nominal operating condition V_{DD} = 3.3 V and with the maximum sampling frequency fs = 400 kHz, the parameters assume the following values:

C_{ia} = 1 pF (max)

R_{mux} = 2 kΩ (max)

R_{sw} = 1.3 kΩ (max)

C_{io} = 7.1 pF (max)

The effective input impedance with these parameters is R_{in} = 308 kΩ.

11.7 ADC usage notes

The following guidelines show how to increase the performance of the ADC in a noisy environment beyond the ADC specifications listed in Table 6:

- The ADC input trace must be short and as close as possible to the LPC11U3x chip.
- Shield The ADC input traces from fast switching digital signals and noisy power supply lines.
- The ADC and the digital core share the same power supply. Therefore, filter the power supply line adequately.
- To improve the ADC performance in a noisy environment, put the device in Sleep mode during the ADC conversion.

11.8 I/O Handler software library applications

The following sections provide application examples for the I/O Handler software library. All library examples make use of the I/O Handler hardware to extend the functionality of the part through software library calls. The libraries are available on http://www.LPCware.com.

11.8.1 I/O Handler I^2S

The I/O Handler software library provides functions to emulate an I^2S master transmit interface using the I/O Handler hardware block.

The emulated I^2S interface loops over a 1 kB buffer, transmitting the datawords according to the I^2S protocol. Interrupts are generated every time when the first 512 bytes have been transmitted and when the last 512 bytes have been transmitted. This allows the ARM core to load the free portion of the buffer with new data, thereby enabling streaming audio.

Two channels with 16-bit per channel are supported. The code size of the software library is 1 kB and code must be executed from the SRAM1 memory area reserved for the I/O Handler code.

11.8.2 I/O Handler UART

The I/O Handler UART library emulates one additional full-duplex UART. The emulated UART can be configured for 7 or 8 data bits, no parity, and 1 or 2 stop bits. The baud rate is configurable up to 115200 baud. The RXD signal is available on three I/O Handler pins (IOH_6, IOH_16, IOH_20), while TXD and CTS are available on all 21 I/O Handler pins.

The code size of the software library is about 1.2 kB and code must be executed from the SRAM1 memory area reserved for the I/O Handler code.

Footprint information for reflow soldering of HVQFN33 package

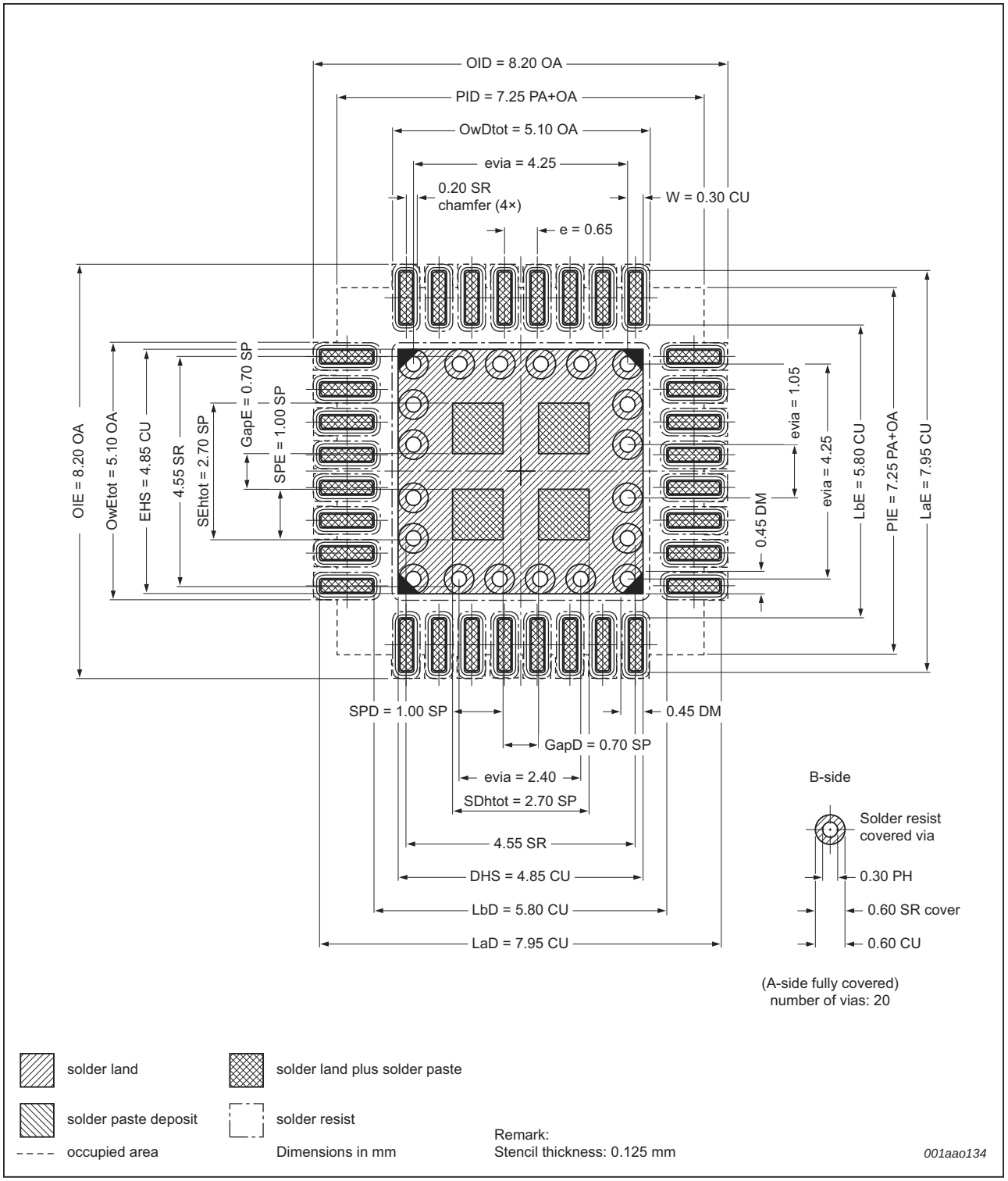


Fig 40. Reflow soldering for the HVQFN33 (7x7) package

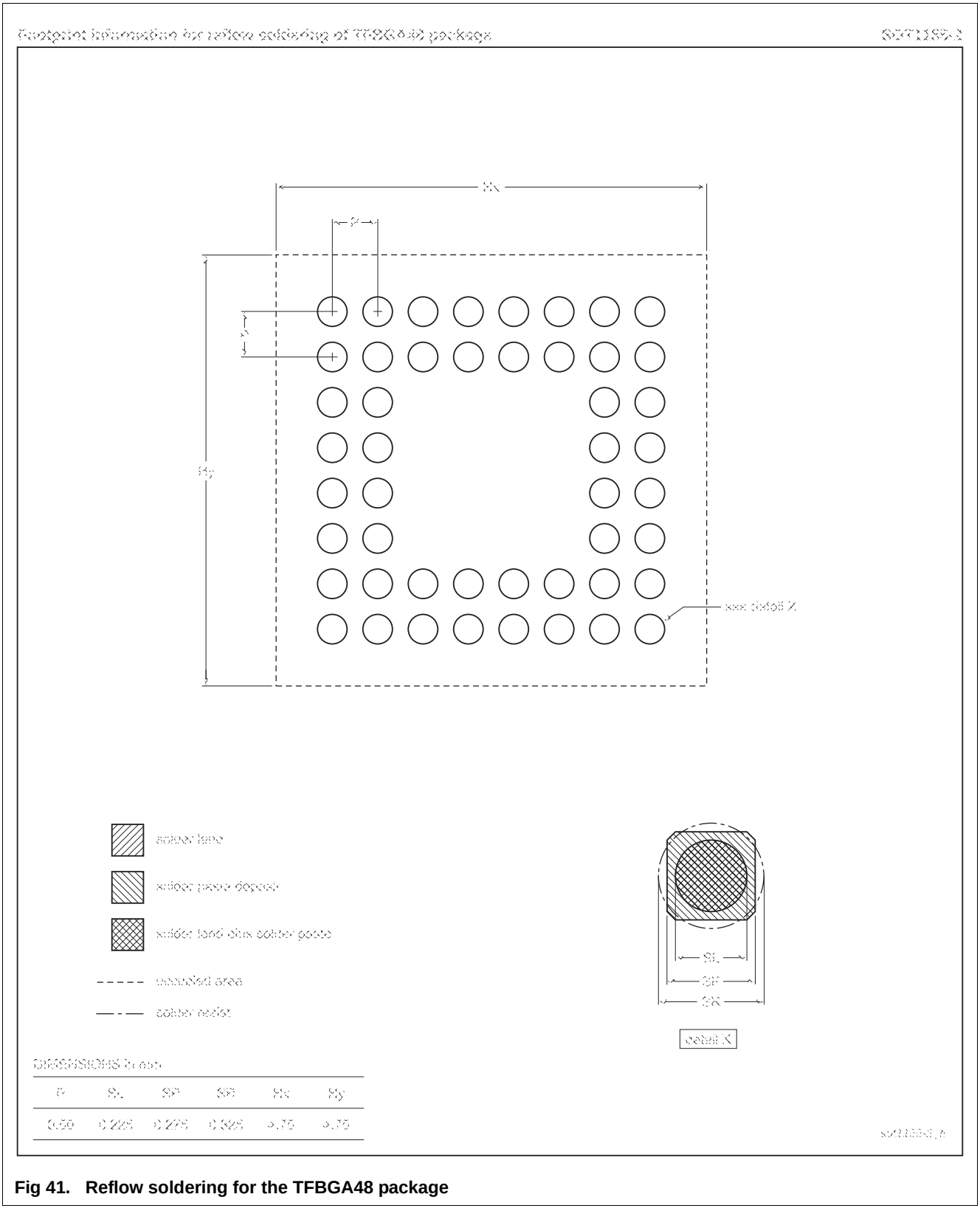
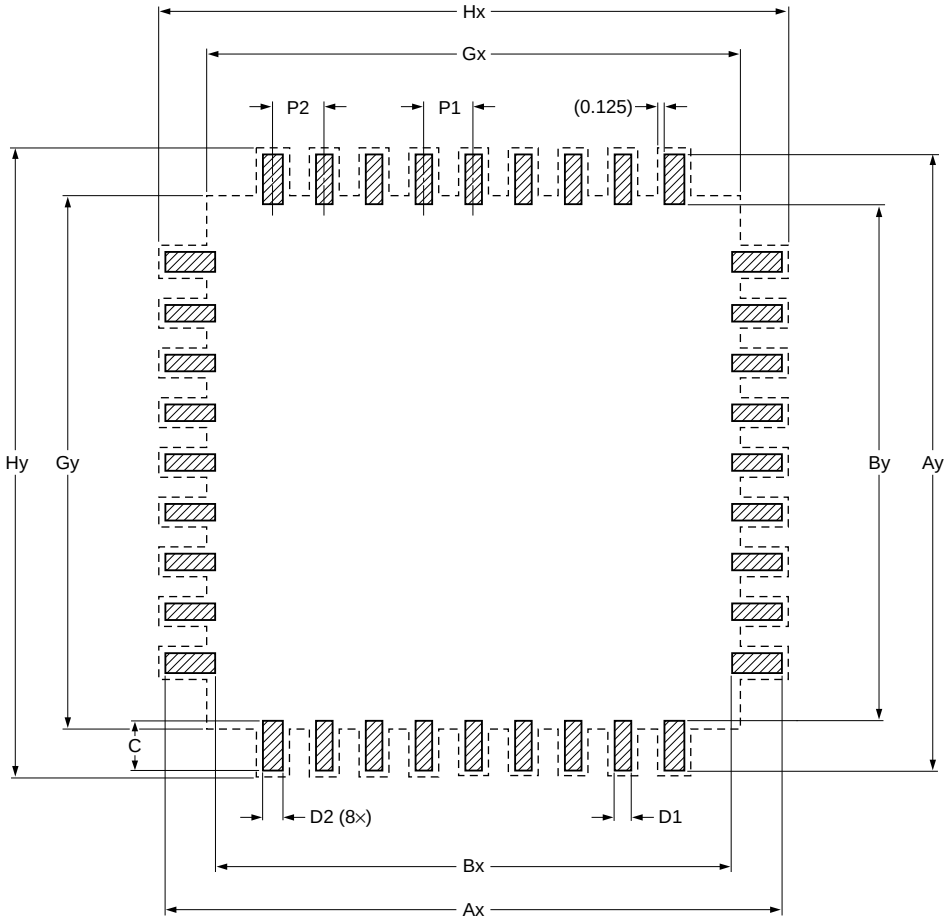


Fig 41. Reflow soldering for the TFBGA48 package

Footprint information for reflow soldering of LQFP64 package **SOT314-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	13.300	13.300	10.300	10.300	1.500	0.280	0.400	10.500	10.500	13.550	13.550

sot314-2_fr

Fig 43. Reflow soldering for the LQFP64 package

14. Abbreviations

Table 20. Abbreviations

Acronym	Description
A/D	Analog-to-Digital
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
BOD	BrownOut Detection
GPIO	General Purpose Input/Output
JTAG	Joint Test Action Group
PLL	Phase-Locked Loop
RC	Resistor-Capacitor
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
TAP	Test Access Port
USART	Universal Synchronous Asynchronous Receiver/Transmitter

15. References

[1] LPC11U3x User manual UM10462:
http://www.nxp.com/documents/user_manual/UM10462.pdf

[2] LPC11U3x Errata sheet:
http://www.nxp.com/documents/errata_sheet/ES_LPC11U3X.pdf

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